

Figures: 1

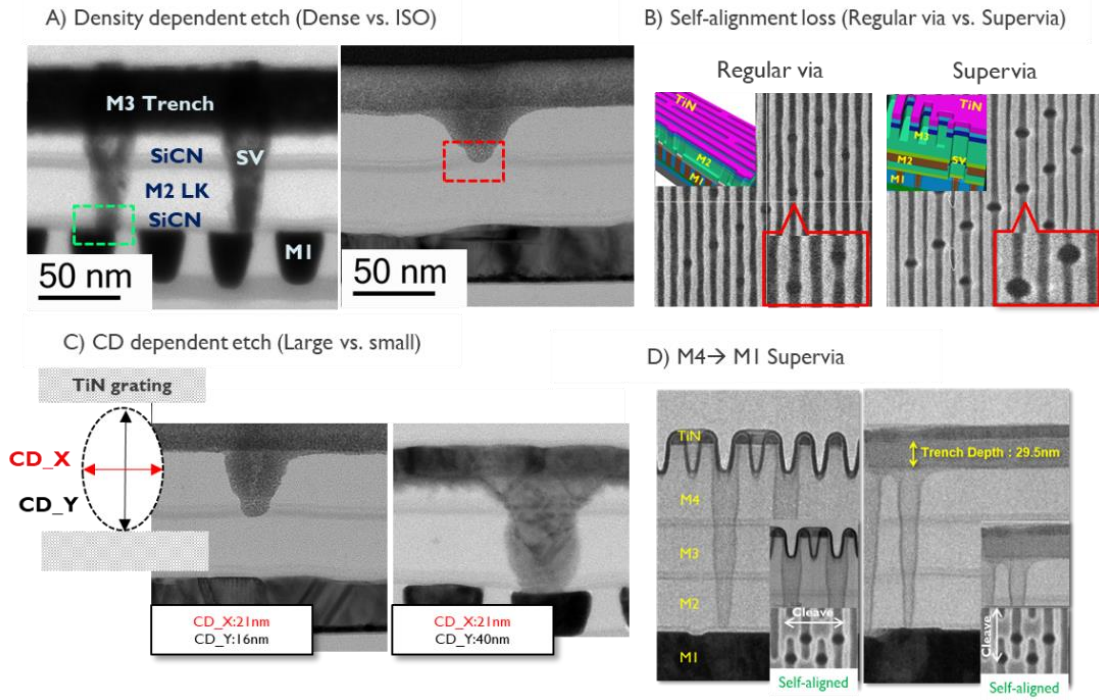


Figure 1: A) Etch loading between dense and iso-vias; B) TD-CDSEM comparison of self-alignment between regular via and supervia; C) CD dependency in supervia etch; D) M4→ M1 supervia with preserved self-alignment, controlled profile, and CD.